


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S005K6T6CTR	9C5V*766XXX	A	959	26-03-2019
	Amount	UoM	Unit type	ST ECOPACK Grade
	180.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
2	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7x1.4	32	L Bend	
Comment	Package : 5V LQFP 32 7x7x1.4 1 0060661			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	9CSV*766XXX				6999999.0	999992.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.500	mg	supplier	die	Silicon (Si)	7440-21-3		4.361	mg	969111	24228
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	2667	67
				supplier	metallization	Copper (Cu)	7440-50-8		0.040	mg	8889	222
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.005	mg	1111	28
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1333	33
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	2444	61
				supplier	Passivation	Silicon Oxide	7631-86-9		0.065	mg	14444	361
Lead-frame	M-011 Other inorganic materials	69.913	mg	supplier	alloy	Copper (Cu)	7440-50-8		67.256	mg	962000	373644
				supplier	alloy	Iron (Fe)	7439-89-6		2.097	mg	30000	11652
				supplier	alloy	Zinc (Zn)	7440-66-6		0.454	mg	6500	2525
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.105	mg	1500	583
Lead-frame Coating	M-011 Other inorganic materials	0.403	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.369	mg	914840	2048
				supplier	coating	Palladium (Pd)	7440-05-3		0.012	mg	29660	66
				supplier	coating	Gold (Au)	7440-57-5		0.011	mg	27750	62
Die Attach	M-011 Other inorganic materials	1.044	mg	supplier	coating	Silver (Ag)	7440-22-4		0.011	mg	27750	62
				supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.804	mg	770000	4468
				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0.236	mg	226000	1311
Wires	M-011 Other inorganic materials	0.645	mg	supplier	glue or soft solder	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.004	mg	4000	23
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.645	mg	1000000	3581
Encapsulation	M-011 Other inorganic materials	103.492	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		7.253	mg	70087	40297
				supplier	Moulding Compound	Phenol Resin	Proprietary		5.181	mg	50062	28783
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		90.384	mg	873343	502132
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.518	mg	5006	2878
Finishing	M-011 Other inorganic materials	0.003	mg	supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.155	mg	1502	864
				supplier	connections coating	Nickel (Ni)	7440-02-0		0.002	mg	914840	13
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	29660	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	27750	0
				supplier	connections coating	Silver (Ag)	7440-22-4		0.000	mg	27750	0